Remarks

Further and favorable reconsideration is respectfully requested in view of the foregoing amendments and following remarks.

Initially, the specification has been amended to make minor idiomatic changes, which are essentially self-explanatory.

Claims 13, 19, 24, 25 and 28 have been amended in response to the rejection of the claims under the second paragraph of 35 U.S.C. §112.

Most of the claim amendments are self-explanatory. But with regard to the amendment to claim 24, Applicants note that this is supported by the disclosure at page 3, line 2 from the bottom, and page 9, lines 7-10 from the bottom of the specification.

In view of the claim amendments, Applicants respectfully submit that the rejection of the claims under the second paragraph of 35 U.S.C. §112 has been rendered moot.

The patentability of the presently claimed invention over the references relied upon by the Examiner in rejecting the claims will be apparent upon consideration of the following remarks.

Thus, the provisional rejection of claims 13-30 for obviousness-type double patenting as being unpatentable over claims 1-9 and 13-17 of Serial No. 11/547,357 is respectfully traversed.

The claims of the '357 application are directed to a resin filled with a number of functional particle aggregates wherein a plurality of functional particles are covered with an insulating material. Further, the '357 claims neither disclose nor suggest that each functional particle is covered with an electrical insulating material comprising at least an inorganic insulating material, and wherein a resin material is fusion-bonded to a surface of the inorganic insulating material so as to partially cover the surface of the functional particle, as required in the claims of the present application.

For these reasons, Applicants take the position that the claims of the present application are patentable over the claims of the '357 application, and therefore, the obviousness-type double patenting rejection should be withdrawn.

The rejection of claims 13-30 under 35 U.S.C. §102(b) as being anticipated by JP 11-256202 is respectfully traversed.

The distinctions between the presently claimed invention and the JP '202 reference are set forth in the English translation of the Response to Written Opinion of August 23, 2005 filed during prosecution of the PCT application on which the present U.S. application is based. A copy of the Response to Written Opinion was filed upon entering the U.S. National Phase, and is listed as item 14(g) of the Transmittal Letter filed February 6, 2006.

Thus, the composite powder of the present invention is, as recited in the present claims, a soft magnetic composite powder characterized in that the surface of the soft magnetic material powder is covered with an electrical insulating material containing at least an inorganic insulating material, and a resin material is fusion-bonded to the surface of the inorganic insulating material so as to **partially** cover the surface of the soft magnetic material powder.

JP '202 does not disclose the feature of the present invention that a resin material is fusion-bonded to the surface of the inorganic insulating material so as to **partially** cover the surface of the soft magnetic material powder, and accordingly, does not anticipate the present invention.

As explained below, the composite powder described in JP '202 has an utterly different structure from that of the composite powder of the present invention.

The raw material powder, as described in paragraph [0025] of JP '202, is produced by weighing the amorphous soft magnetic alloy powder in an amount of 80% by volume, the glass powder in an amount of 10% by volume, and the epoxy resin powder in an amount of 10% by volume, loading them into a ball mill, and mixing them for 24 hours. As common knowledge in this industrial field, in the case of mixing these three components, the amorphous soft magnetic alloy powder, the glass powder, and the epoxy resin powder by a ball mill, it gives a composite powder containing the amorphous soft magnetic alloy powder and the glass powder **entirely** covered with the resin powder which is the softest and most deformable among these three components, and bonded with each other by the resin powder.

As described in paragraph [0026], another raw material powder is produced by loading a powder of composite particles each comprising a mother particle of an amorphous soft magnetic alloy and a glass layer covering the surface of the mother particle together with a binder resin powder into a ball mill and mixing them for 24 hours. With respect to the raw material powder, although the surface of the soft magnetic material powder is covered with the glass layer, which is an inorganic insulating material, if the powder is mixed by a ball mill for 24 hours, only a composite powder of which the glass layer is **entirely** covered with the binder resin is obtained.

As described in paragraph [0027], another raw material powder is produced by weighing 80% by volume of an amorphous soft magnetic alloy, 10% by volume of a glass powder, and 10% by volume of an epoxy resin powder, loading them into a powder coating apparatus, and forming a layer of the glass and epoxy resin on the surface of the mother particles of the amorphous soft magnetic alloy powder. Accordingly, similarly to the first raw material powder above, the **entire** surface of the soft magnetic material powder is **completely** covered with the resin material.

According to the present invention, on the other hand, since the resin material **partially** covers the surface of the soft magnetic material powder, the resin material can freely be deformed as compared with the case of entirely covering the surface, that is, the resin material is freely deformable on the fused point of the inorganic insulating material as a supporting point, and the particles of the soft magnetic material brought into contact with the resin material change the moving direction owing to the deformation of the resin material, and are enabled to move to the voids among the powder particles. Consequently, it is possible to increase the packing density with low pressures.

However, with respect to the raw material powders of JP '202, since the surface of the soft magnetic material powder is **completely** covered with the resin material, the deformability of the resin material is low and the soft magnetic material powder is difficult to move and the packing density cannot be improved unless rather high press-pressure is applied as compared with that in the case of the present invention.

For these reasons, Applicants take the position that the presently claimed invention is clearly patentable over the JP '202 reference, and therefore, the rejection of the claims as being anticipated by this reference should be withdrawn.

Accordingly, in view of the foregoing amendments and remarks, it is submitted that each of the grounds of rejection set forth by the Examiner has been overcome, and that the application is in condition for allowance. Such allowance is solicited.

Respectfully submitted,

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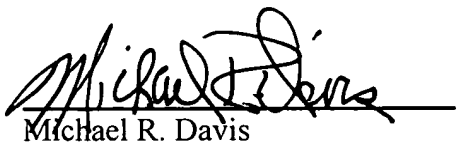
By: 

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